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APPLICANT: YAMADA SEISAKUSHO:KK;

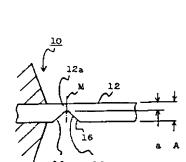
INVENTOR: ANDO MAKOTO;

INT.CL.

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TITLE

SEMICONDUCTOR DEVICE



16

12b L 12

ABSTRACT :

PURPOSE: To form a bent part readily by only bending a lead pin without yielding micro-cracks, by forming the bent part of the lead pin, which is extended from a semiconductor package, so that the bent part is thinner than the other part.

CONSTITUTION: The bent part of a lead pin 12, which is extended from a semiconductor package 14, is made thinner than the other part of the lead pin 12. The thin bending part is bent. When the lead pin 12 is bent downward with a bending position M as a center, facing surfaces 16a and 16a of a cut-out part 16 are brought close together. The thickness (a) of the bent part 12a is thinner than the thickness A of the lead pin (a<A). Therefore a deforming range (I), when the lead pin 12 is bent, is narrower than a deforming range L when the cut-out part 16 is not provided (I<L). Therefore, the deforming range of the lead pin 12 does not reach the extended edge of the package 14, in which the lead pin 12 is sealed.

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